



Special PCB in PCBgate

PCB Manufacturing Capacity

Item	Specification
Material	FR-4, FR1,FR2, CEM-1,CEM-3; Rogers,Teflon,Arlon; Aluminum Base, Copper Base,Ceramic ,etc.
Remarks	High Tg CCL is Available($T_g \geq 180^\circ\text{C}$)
Finish Board Thickness	0.2 mm~6.00mm(8mil-126mil)
Surface Finish	Gold finger($\geq 0.13\mu\text{m}$), Immersion Gold(0.025-0075um), Plating Gold(0.025-3.0um), HASL(5-20um), OSP(0.2-0.5um)
Shape	Routing、Punch、V-cut、Chamfer
Surface Treatment	Solder Mask(black, green, white, red, blue, thickness $\geq 12\mu\text{m}$, Block, BGA)
	Silkscreen(black, yellow, white)
	Peel able-mask(red, blue, thickness $\geq 300\mu\text{m}$)
Minimum Core	0.075mm(3mil)
Copper Thickness	1/2 oz min; 12oz max
Min Trace Width & Line Spacing	0.075mm/0.075mm(3mil/3mil)
Min Hole Diameter for CNC Drilling	0.1mm(4mil)
Min Hole Diameter for Punching	0.6mm(35mil)
Biggest panel size	2000mm * 700mm
Hole Position	+/-0.075mm(3mil) CNC Drilling
Conductor Width(W)	+/-0.05mm(2mil) or +/-20% of original
Hole Diameter(H)	PTH: +/-0.075mm(3mil)
	Non PTH: +/-0.05mm(2mil)
Outline Tolerance	+/-0.1mm(4mil) CNC Routing
Warp & Twist	0.70%
Insulation Resistance	10Kohm-20Mohm
Conductivity	<50ohm
Test Voltage	10-300V
Panel Size	110 x 100mm(min)
	2000 x 700mm(max)
Layer-layer misregistration	4 layers:0.15mm(6mil)max
	6 layers:0.25mm(10mil)max
Min spacing between hole edge to circuitry pattern of an inner layer	0.25mm(10mil)
Min spacing between board outline to circuitry pattern of an inner layer	0.25mm(10mil)
Board thickness tolerance	4 layers: +/-0.13mm(5mil)